

Abstract

The present invention relates to an integrated circuit system with at least one integrated circuit, a cooling body to dissipate the heat generated by the integrated circuit
5 and a latent heat storage module having a latent heat storage medium. The latent heat storage module is thermally connected to the cooling body in order to temporarily store the heat generated by the integrated circuit and to convey it to the cooling body. The integrated circuit has at least
10 one semiconductor component which is assembled on a substrate and the substrate is in direct thermal contact with the latent heat storage module.